

APPROVAL SHEET

RGBLN 2012 (0805) Series – RoHS Compliance
MULTILAYER CERAMIC BALUN TRANSFORMER
Halogens Free Product

2.4 GHz ISM Band Working Frequency

P/N:RGBLN2012080A6T

*Contents in this sheet are subject to change without prior notice.

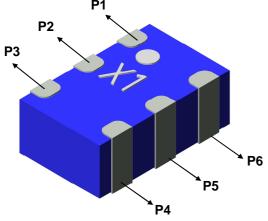
FRATURES

- 1. Multilayer LTCC (Low Temperature Cofired Ceramics) Technology
- 2. Miniatured Size 2.00 x 1.25 x 0.85 mm³
- 3. Low Insertion Loss reduces power consumption
- 4. Low inband Amplitude and Phase imbalance enable high performance wireless system operation.
- 5. Enable for DC Biasing of PA or Mixer
- 6. Suitable for 2.45 GHz Working Frequency Operation
- 7. Special Balance/ Unbalance impedance is upon requested.

APPLICATIONS

- 1. 2.4GHz ISM Band RF Application
- 2. Bluetooth, Wireless LAN, HomeRF

CONSTRUCTION



PIN	Connection	PIN	Connection
1	Unbalance Port	4	Balance Port
2	DC or GND	5	GND
3	Balance Port	6	NC

DESCRIPTION

Walsin Technology Corporation develops a new ceramic Balun Transformer specified for 2.45 GHz ISM Band application, as shown in fig-1. Both of Wireless LAN IEEE 802.11b, and BluetoothTM typically located on this unlicensed frequency band which range covers from 2.4GHz to 2.5GHz (2.4835GHz). To fulfil the in-band and out-band frequency requirements, this ceramic Balun has been designed to a low Amplitude imbalance and Phase imbalance, wide bandwidth (-10dB) as well as low insertion loss characteristics through Walsin's advanced LTCC (Low Temperature Co-fired Ceramic) technology and superior product design via 3D EM Simulation Skill.

This ceramic Balun has a rectangular ceramic body with a tiny dimension of 2.00 x 1.25 x 0.85 mm³ future meet the SMT automation and miniaturization requirements on modern portable devices.

DIMENSIONS

Figure			Symbol	Dimension
	T		L	2.00 ± 0.15 mm
		A B	W	1.25 ± 0.15 mm
V1 -		C	Т	0.80± 0.10 mm
	L -		А	0.20 ± 0.15 mm
		D	В	0.30 ± 0.20 mm
	,		С	0.35 ± 0.20 mm
	W	T	D	0.65 ± 0.20 mm

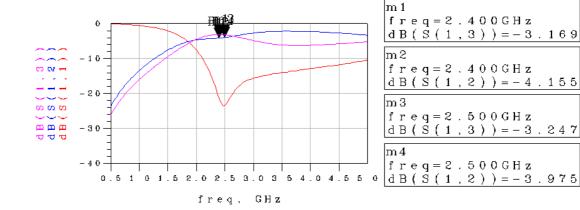


ELECTRICAL CHARACTERISTICS

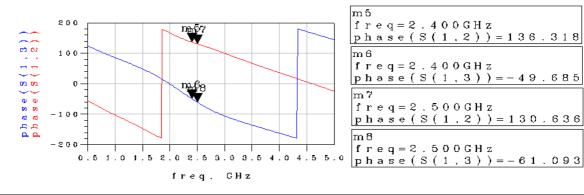
RGBLN2012080A6T	Specification
Frequency range	2450 ± 50 MHz
Insertion Loss	1 dB max
Impedance (Unbalanced)	50 Ω
Impedance (Balanced)	100 Ω
Return Loss (dB) Min.	20 dB
Phase Difference	180° ± 20°
Amplitude Balance	2 .0 dB Max
Operating temperature Range	-40℃~85℃

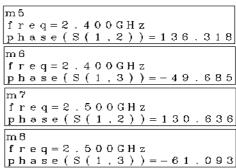
Typical Electrical Chart

(1). Amplitude balance



(2). Phase balance





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SOLDER LAND PATTERN

Figure	Symbol	Dimension (mm)
D	A	1.00 ± 0.10
	В	0.35 ± 0.10
	С	0.30 ± 0.10
	D	0.65 ± 0.10
ш	Е	0.80 ± 0.10
Unit: mm	Line width to be design to r material and thickness	match 50Ω characteristic impedance, depending on PCB



RELIABILITY TEST

*Solder bath temperature : $235 \pm 5^{\circ}$ C *Immersion time : 2 ± 0.5 sec *Solder : Sn3Ag0.5Cu for lead-free *Solder bath temperature : $260 \pm 5^{\circ}$ C *Leaching immersion time : 30 ± 0.5 sec *Solder : SN63A	At least 95% of a surface of each terminal electrode must be covered by fresh solder. Loss of metallization on the edges of each electrode shall not exceed 25%.
*Solder : Sn3Ag0.5Cu for lead-free *Solder bath temperature : $260 \pm 5^{\circ}$ C *Leaching immersion time : 30 ± 0.5 sec *Solder : SN63A	Loss of metallization on the edges of each
*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	· ·
*Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	· ·
*Preheating temperature∶ 120~150°C,	
1 minute.	No mechanical damage. Samples shall satisfy electrical specification after test.
*Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free	Loss of metallization on the edges of each electrode shall not exceed 25%.
Measurement to be made after keeping at room temperature for 24±2 hrs	
*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units: 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
*Pressurizing force : 5N(≤0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at	No mechanical damage. Samples shall satisfy electrical specification after test.
	*Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs *Height : 75 cm *Test Surface : Rigid surface of concrete or steel. *Times : 6 surfaces for each units ; 2 times for each side. *Pressurizing force : 5N(≤0603) ; 10N(>0603) *Test time : 10±1 sec The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1

Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
JIS C 0025	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency: 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude : 1.5mm	Samples shall satisfy electrical specification
	*Test times : 6hrs.(Two hrs each in three	after test.
	mutually perpendicular directions)	
High temperature	,	
JIS C 0021	*Temperature: 85°C±2°C	No mechanical damage.
	*Test duration: 1000+24/-0 hours	Samples shall satisfy electrical specification after test.
	Measurement to be made after keeping at	alter test.
	room temperature for 24±2 hrs	
Humidity	*Humidity: 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification
JIS C 0022	*Time: 1000+24/-0 hrs.	after test.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration: 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

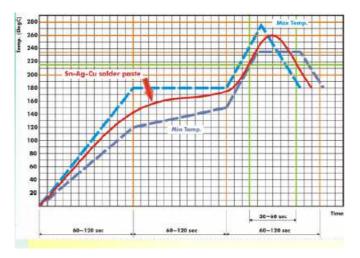


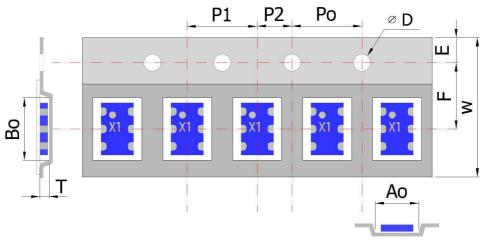
Fig 2. Infrared soldering profile

ORDERING CODE

RG	BLN	201208	0	Α	6	Т
Walsin	Product Code	Dimension	Unit of	Application	Specification	Packing
RG: RF	BLN : BALUN	code	dimension	A: 2.4GHZ ISM	Design Code	T:7" Reeled
/Pb free		Per 2 digits of	0 : 0.1 mm	Band		
device		Length, Width, Thickness:	1 : 1.0 mm			
		e.g. : 201208 =				
		Length 20,				
		Width 12,				
		Thickness 08				

Minimum Ordering Quantity: 2000 pcs per reel.

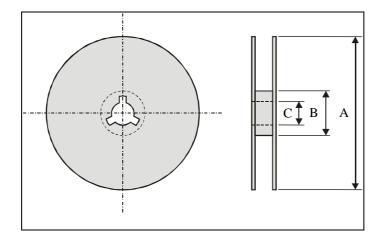
PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.35 ± 0.10	2.30 ± 0.10	1.55 ± 0.10	0.95 ± 0.10	8.0 ± 0.30
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10

Reel dimensions



Index	А	В	С
Dimension (mm)	Ф178.0	Ф60.0	Ф13.0

Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.